

MICHAEL HUMMEL

Executive Vice President Front-End Manufacturing, Analog and Power STMicroelectronics

Michael Hummel is Executive Vice President of STMicroelectronics, Analog and Power Front-End Manufacturing, and has held this position since March 2019.

In 1991, Hummel started his professional career with IBM Microelectronics as a Process Engineer at Europe's first 200mm wafer fab in Böblingen, Germany. He held several managerial positions in Manufacturing and Engineering and became Director of Marketing & Supply Chain Management for the Philips-IBM JV in 1996. In the early 2000s, Hummel served as VP of Philips' Display Driver business – first in Zürich and later in Taipei. In 2005, he was promoted to VP and General Manager of Philips Semiconductors Germany and Head of the Wafer Fab Operation in Böblingen. In 2007, Hummel joined Texas Instruments as Operations Manager in Dallas and two years later became Fab Manager at the Freising, Germany wafer plant. Upon TI's acquisition of National Semiconductors in 2011, Hummel assumed additional responsibility for the Greenock, UK wafer fab and its integration into TI's Front-End Fab structure.

Hummel sat on SEMI European Advisory Board in 2005-2017.

Michael Hummel was born in Heilbronn, Germany, in 1959. He studied Chemistry at the University of Tübingen and received his PhD degree in Organic & Physical Chemistry in 1991.